Silicon N Channel MOS FET Series Power Switching

HITACHI

ADE-208-503 A (Z) 2nd. Edition October 1997

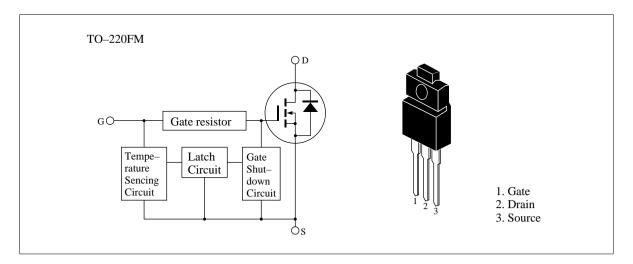
Features

This FET has the over temperature shut-down capability sensing to the junction temperature.

This FET has the built-in over temperature shut-down circuit in the gate area. And this circuit operation to shut-down the gate voltage in case of high junction temperature like applying over power consumption, over current etc.

- Logic level operation (4 to 6 V Gate drive)
- High endurance capability against to the short circuit
- Built–in the over temperature shut–down circuit
- Latch type shut–down operation (Need 0 voltage recovery)

Outline





Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	60	V	
Gate to source voltage	V _{GSS}	16	V	
Gate to source voltage	V _{GSS}	-2.8	V	
Drain current	I _D	20	А	
Drain peak current	Note1 D(pulse)	40	А	
Body-drain diode reverse drain current	I _{DR}	20	А	
Channel dissipation	Pch Note2	30	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Note: 1. PW \leq 10µs, duty cycle \leq 1 %

2. Value at Ta = 25° C

Typical Operation Characteristics

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Input voltage	V _{IH}	3.5	_	_	V	
	V _{IL}	_	—	1.2	V	
Input current	I _{IH1}	—	—	100	μA	$Vi = 8V, V_{DS} = 0$
(Gate non shut down)	I _{IH2}	_	_	50	μA	Vi = 3.5V, V _{DS} = 0
	I _{IL}	_	_	1	μA	Vi = 1.2V, V _{DS} = 0
Input current	I IH(sd)1	—	0.8	—	mA	$Vi = 8V, V_{DS} = 0$
(Gate shut down)	I _{IH(sd)2}	_	0.35	_	mA	Vi = 3.5V, V _{DS} = 0
Shut down temperature	T_{sd}	_	175	—	°C	Channel temperature
Gate operation voltage	V _{OP}	3.5	—	13	V	

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions	
Drain current	I _{D1}	10	_		А	$V_{GS} = 3.5V, V_{DS} = 2V$	
Drain current	I _{D2}	_	_	10	mA	$V_{GS} = 1.2V, V_{DS} = 2V$	
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	60	—	_	V	$I_{\rm D} = 10 {\rm mA}, V_{\rm GS} = 0$	
Gate to source breakdown voltage	$V_{(BR)GSS}$	16	—	—	V	$I_{G} = 100 \mu A, V_{DS} = 0$	
Gate to source breakdown voltage	$V_{(\text{BR})\text{GSS}}$	-2.8	—	_	V	$I_{g} = -100 \mu A, V_{DS} = 0$	
Gate to source leak current	I _{GSS1}	_		100	μΑ	$V_{GS} = 8V, V_{DS} = 0$	
	I _{GSS2}	_	_	50	μA	$V_{GS} = 3.5V, V_{DS} = 0$	
	I _{GSS3}			1	μA	$V_{GS} = 1.2V, V_{DS} = 0$	
	I _{GSS4}	_		-100	μA	$V_{GS} = -2.4V, V_{DS} = 0$	
Input current (shut down)	I _{GS(op)1}	—	0.8	—	mA	$V_{GS} = 8V, V_{DS} = 0$	
	I _{GS(op)2}	—	0.35	_	mA	$V_{GS} = 3.5V, V_{DS} = 0$	
Zero gate voltege drain current	I _{DSS}	—	—	250	μΑ	$V_{\rm DS} = 50$ V, $V_{\rm GS} = 0$	
Gate to source cutoff voltage	V _{GS(off)}	1.0		2.25	V	$I_{\rm D} = 1$ mA, $V_{\rm DS} = 10$ V	
Static drain to source on state resistance	$R_{DS(on)}$	_	50	65	mΩ	$I_{\rm D}=10A, \ V_{\rm GS}=4V^{\rm Note3}$	
Static drain to source on state resistance	$R_{DS(on)}$	—	30	43	mΩ	$I_{D} = 10A, V_{GS} = 10V^{Note3}$	
Forward transfer admittance	y _{fs}	6	12		S	$I_{\rm D} = 10$ A, $V_{\rm DS} = 10 V^{\rm Note3}$	
Output capacitance	Coss	_	630	_	pF	$V_{DS} = 10V$, $V_{GS} = 0$ f = 1 MHz	
Turn-on delay time	t _{d(on)}	_	7.5	_	μs	$I_{\rm D} = 5A, V_{\rm GS} = 5V$	
Rise time	t,	_	29	_	μs	$R_{L} = 6\Omega$	
Turn-off delay time	t _{d(off)}		34		μs		
Fall time	t _f	_	26	_	μs		
Body-drain diode forward	V_{DF}	_	1.0	_	V	$I_{\rm F} = 20$ A, $V_{\rm GS} = 0$	
voltage							
Body-drain diode reverse	t _{rr}	_	110	_	ns	$I_{\rm F} = 20$ A, $V_{\rm GS} = 0$	
recovery time						diF/ dt =50A/µs	
Over load shut down	t _{os1}	_	1.8		ms	$V_{\rm GS}=5V,~V_{\rm DD}=12V$	
operation time Note4	t _{os2}		0.7	_	ms	$V_{GS} = 5V, V_{DD} = 24V$	

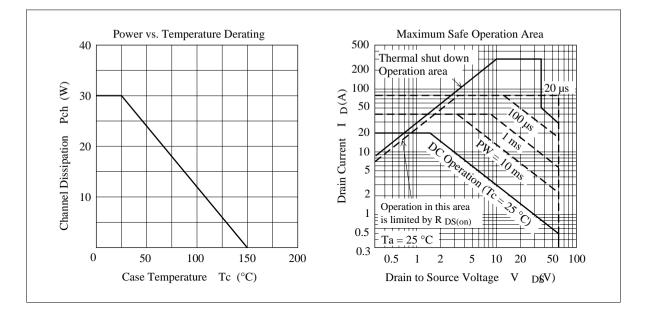
Note: 3. Pulse test

4. Include the time shift based on increasing of channel temperature when operate under over load condition.

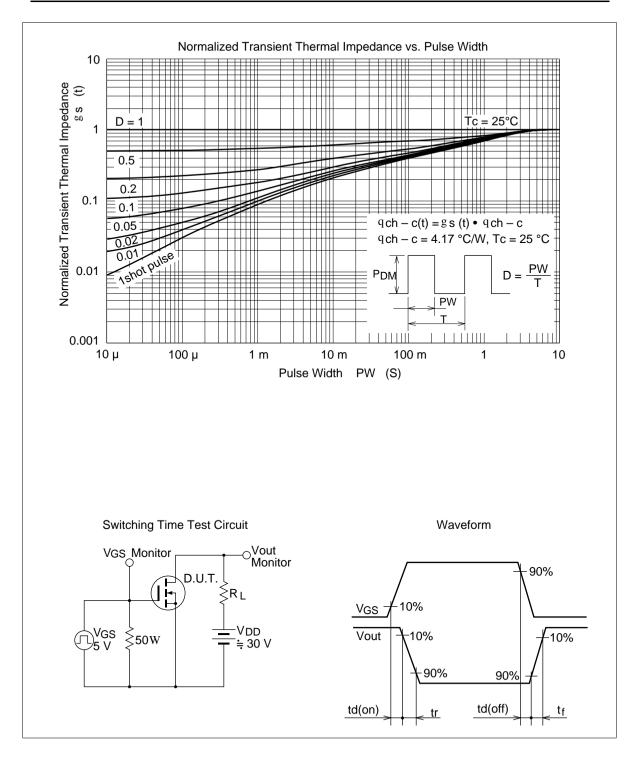
See characteristic curve of HAF2001.

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Main Characteristics



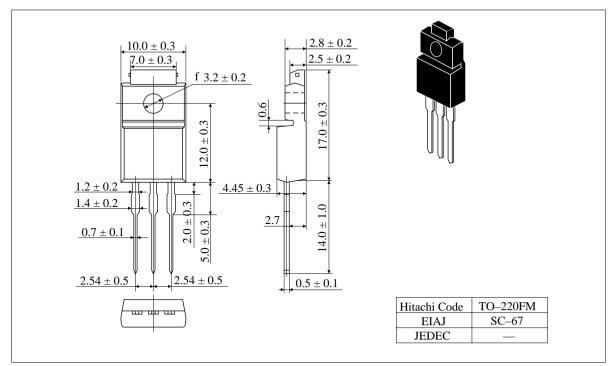
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Package Dimensions

Unit: mm



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